

HVC316

Variable Capacitance Diode for BS/CS tuner

REJ03G0516-0100 (Previous: ADE-208-1124) Rev.1.00 Feb 16, 2005

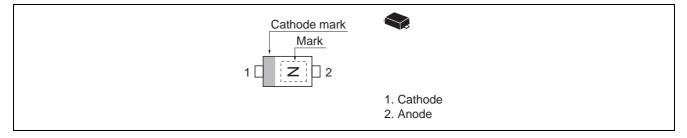
Features

- High capacitance ratio (n = 9.0 min)
- Low series resistance. ($r_s = 2.2 \Omega max$)
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Renesas Code	Previous Code
HVC316	Ν	PWSF0002ZA-A	UFP

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	30	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

 $(Ta = 25^{\circ}C)$ ltem Symbol Max Unit **Test Condition** Min Тур 10 V_R = 30 V Reverse current I_{R1} nA ____ ____ 100 V_R = 30 V, Ta = 60°C I_{R2} ____ ____ Capacitance C_1 5.16 7.22 V_R = 1 V, f = 1 MHz ____ pF V_R = 25V, f = 1 MHz C₂₅ 0.48 0.76 ___ Capacitance ratio C₁ / C₂₅ n 9.0 _ 2.20 Series resistance V_R = 1 V, f = 470 MHz rs — Ω ____ $\Delta C/C *^1$ ____ 6.00 V_{R} = 1 to 25 V, f = 1 MHz Matching error ____ %

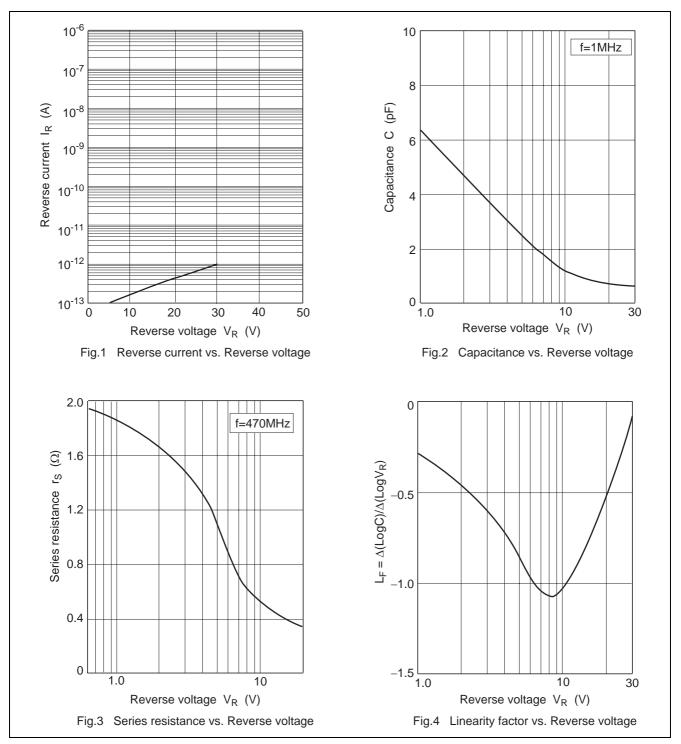
Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of ∆C/C continuous in a reel , expect extention to another group.

Calculate Matching Error,

 $\Delta C/C = \frac{(Cmax - Cmin)}{Cmin} \times 100 \ (\%)$

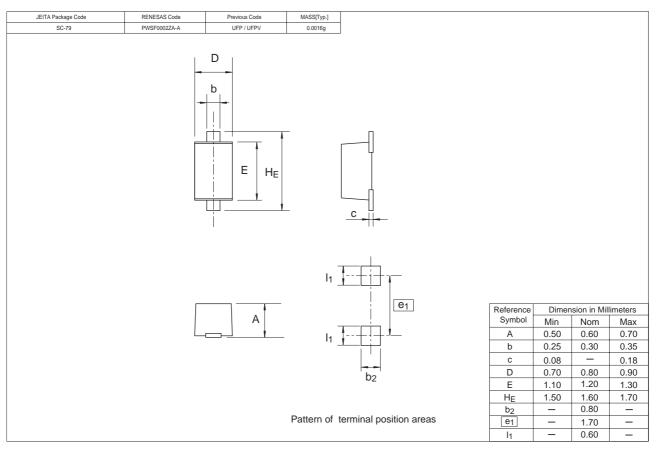


Main Characteristic





Package Dimensions





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